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Date: 12/22/05

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney's Docket No.: JG-SU-5221/500577.20071

U.S. Application No.:

International Application No.: PCT/JP2004/015999

International Filing Date: OCTOBER 28, 2004

28 OCTOBER 2004

Priority Date Claimed: DECEMBER 10, 2003

10 DECEMBER 2003

Title of Invention: PROCESSING METHOD OF SILICON WAFER

Applicant(s) for (DO/EO/US): Sakae KOYATA and Kazushige TAKAISHI

Mail Stop PCT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313 1450

PRELIMINARY AMENDMENT

Sir:

The above-identified application is filed concurrently herewith, please amend the specification as follows:

Amendments to the specification begin on page 2 of this paper.

Amendments to the Abstract begin on page 3 of this paper.

Remarks / Arguments begin on page 4 of this paper.